Intel - EPF10K250EFC672-2 Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	-
Number of Gates	-
Voltage - Supply	-
Mounting Type	Surface Mount
Operating Temperature	-
Package / Case	672-BBGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epf10k250efc672-2

- Software design support and automatic place-and-route provided by the Altera MAX+PLUS® II development system for 486- and Pentium-based PCs, Sun SPARCstation, HP 9000 Series 700/800, and IBM RISC System/6000 workstations
- Flexible package options
  - Available in a variety of packages with 144 to 672 pins, including the innovative FineLine BGA™ packages (see Tables 3 and 4)
  - SameFrame™ pin-compatibility (with other FLEX 10KE devices) across device densities and pin counts
- Additional design entry and simulation support provided by electronic design interchange format (EDIF) 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), DesignWare components, Verilog HDL, VHDL, and other interfaces to popular electronic design automation (EDA) tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, Synplicity, VeriBest, and Viewlogic

Table 3. FLEX 10KE Package Options & I/O Pin Count *Notes (1), (2), (3)*

Device	144-Pin TQFP	208-Pin PQFP	240-Pin PQFP	256-Pin FineLine BGA	356-Pin BGA	484-Pin FineLine BGA	599-Pin PGA	600-Pin BGA	672-Pin FineLine BGA
EPF10K30E	102	147		176		220			
EPF10K50E	102	147	189	191		254			
EPF10K100B		147	189	191					
EPF10K100E		147	189	191	274	338			
EPF10K130E			186			369			413
EPF10K200E							470	470	470
EPF10K250E							470	470	470

Notes:

(1) Contact Altera Customer Marketing for up-to-date information on package availability.

(2) FLEX 10KE device package types include thin quad flat pack (TQFP), plastic quad flat pack (PQFP), pin-grid array (PGA), and ball-grid array (BGA).

(3) Devices in the same package are pin-compatible, although some devices have more I/O pins than others. When planning device migration, use the I/O pins that are common to all devices. MAX+PLUS II software versions 9.1 and higher provide features to help use only the common pins.

Table 4. FLEX 10KE Package Sizes

Device	144-Pin TQFP	208-Pin PQFP	240-Pin PQFP	256-Pin FineLine BGA	356-Pin BGA	484-Pin FineLine BGA	599-Pin PGA	600-Pin BGA	672-Pin FineLine BGA
Pitch (mm)	0.50	0.50	0.50	1.0	1.27	1.0	–	1.27	1.0
Area (mm^2)	484	936	1,197	289	1,225	529	3,904	2,025	729

Table 6 shows FLEX 10KE performance for more complex designs. These designs are available as Altera MegaCore™ functions.

Table 6. FLEX 10KE Performance for Complex Designs

Application	LEs Used	Performance			Units
		-1 Speed Grade	-2 Speed Grade	-3 Speed Grade	
16-bit, 8-tap parallel finite impulse response (FIR) filter	592	138	128	103	MSPS
8-bit, 512-point fast Fourier transform (FFT) function	1,845	60	72	83	µs
		76	66	56	MHz
a16450 universal asynchronous receiver/transmitter (UART)	479	42	39	34	MHz

The FLEX 10KE architecture is similar to that of embedded gate arrays, which is the fastest-growing segment of the gate array market. As with standard gate arrays, embedded gate arrays implement general logic in a conventional "sea-of-gates" architecture. Additionally, embedded gate arrays have dedicated die areas for implementing large, specialized functions. By embedding functions in silicon, embedded gate arrays provide reduced die area and increased speed compared to standard gate arrays. While embedded megafunctions typically cannot be customized, FLEX 10KE devices are programmable, providing the designer with full control over embedded megafunctions and general logic while facilitating iterative design changes during debugging.

Each FLEX 10KE device contains an embedded array and a logic array. The embedded array is used to implement a variety of memory functions or complex logic functions, such as digital signal processing (DSP), microcontroller, wide-data-path manipulation, and data-transformation functions. The logic array performs the same function as the sea-of-gates in the gate array: it is used to implement general logic, such as counters, adders, state machines, and multiplexers. The combination of embedded and logic arrays provides the high performance and high density of embedded gate arrays, enabling designers to implement an entire system on a single device.

FLEX 10KE devices are configured at system power-up with data stored in an Altera serial Configuration EPROM device or provided by a system controller. Altera offers the EPC1, EPC2, and EPC1441 Configuration EPROMs, which configure FLEX 10KE devices via a serial data stream. Configuration data can also be downloaded from system RAM or from the Altera BitBlaster™ serial download cable, ByteBlaster™ parallel port download cable, or ByteBlasterMV™ parallel port download cable. After a FLEX 10KE device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Because reconfiguration requires less than 330 ms, real-time changes can be made during system operation.

FLEX 10KE devices contain an optimized interface that permits microprocessors to configure FLEX 10KE devices serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat a FLEX 10KE device as memory and configure the device by writing to a virtual memory location, making it very easy for the designer to reconfigure the device.

For more information, go to the following documents:

- *Configuration EPROMs for FLEX Devices Data Sheet*
- *BitBlaster Serial Download Cable Data Sheet*
- *ByteBlaster Parallel Port Download Cable Data Sheet*
- *ByteBlasterMV Parallel Port Download Cable Data Sheet*

FLEX 10KE devices are supported by the Altera MAX+PLUS II development system, a single, integrated package that offers schematic, text—including AHDL—and waveform design entry; compilation and logic synthesis; full simulation and worst-case timing analysis; and device configuration. The MAX+PLUS II software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX workstation-based EDA tools.

The MAX+PLUS II software works easily with common gate array EDA tools for synthesis and simulation. For example, the MAX+PLUS II software can generate Verilog HDL files for simulation with tools such as Cadence Verilog-XL. Additionally, the MAX+PLUS II software contains EDA libraries that use device-specific features such as carry chains, which are used for fast counter and arithmetic functions. For instance, the Synopsys Design Compiler library supplied with the MAX+PLUS II development system includes DesignWare functions that are optimized for the FLEX 10KE architecture.

An EAB is fed by a row interconnect and can drive out to row and column interconnects. Each EAB output can drive up to two row channels and up to two column channels; the unused row channel can be driven by other LEs. This feature increases the routing resources available for EAB outputs (see Figures 2 and 3). The column interconnect, which is adjacent to the EAB, has twice as many channels as other columns in the device.

Logic Array Block

A LAB consists of eight LEs, their associated carry and cascade chains, LAB control signals, and the LAB local interconnect. The LAB provides the coarse-grained structure to the FLEX 10KE architecture, facilitating efficient routing with optimum device utilization and high performance (see Figure 6).

The programmable flipflop in the LE can be configured for D, T, JK, or SR operation. The clock, clear, and preset control signals on the flipflop can be driven by global signals, general-purpose I/O pins, or any internal logic. For combinatorial functions, the flipflop is bypassed and the output of the LUT drives the output of the LE.

The LE has two outputs that drive the interconnect; one drives the local interconnect and the other drives either the row or column FastTrack Interconnect routing structure. The two outputs can be controlled independently; for example, the LUT can drive one output while the register drives the other output. This feature, called register packing, can improve LE utilization because the register and the LUT can be used for unrelated functions.

The FLEX 10KE architecture provides two types of dedicated high-speed data paths that connect adjacent LEs without using local interconnect paths: carry chains and cascade chains. The carry chain supports high-speed counters and adders; the cascade chain implements wide-input functions with minimum delay. Carry and cascade chains connect all LEs in a LAB and all LABs in the same row. Intensive use of carry and cascade chains can reduce routing flexibility. Therefore, the use of these chains should be limited to speed-critical portions of a design.

Carry Chain

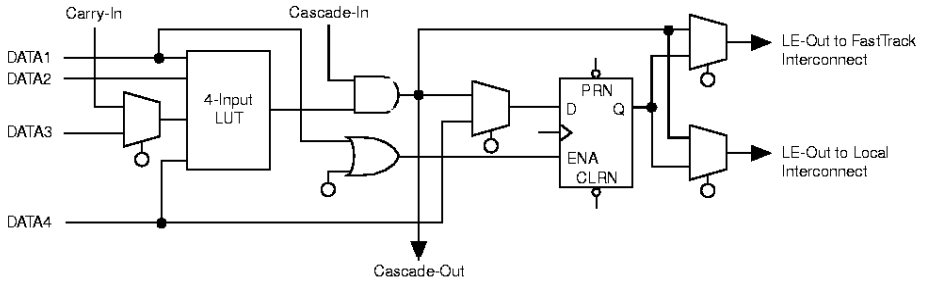
The carry chain provides a very fast (as low as 0.2 ns) carry-forward function between LEs. The carry-in signal from a lower-order bit drives forward into the higher-order bit via the carry chain, and feeds into both the LUT and the next portion of the carry chain. This feature allows the FLEX 10KE architecture to implement high-speed counters, adders, and comparators of arbitrary width efficiently. Carry chain logic can be created automatically by the MAX+PLUS II Compiler during design processing, or manually by the designer during design entry. Parameterized functions such as LPM and DesignWare functions automatically take advantage of carry chains.

Carry chains longer than eight LEs are automatically implemented by linking LABs together. For enhanced fitting, a long carry chain skips alternate LABs in a row. A carry chain longer than one LAB skips either from even-numbered LAB to even-numbered LAB, or from odd-numbered LAB to odd-numbered LAB. For example, the last LE of the first LAB in a row carries to the first LE of the third LAB in the row. The carry chain does not cross the EAB at the middle of the row. For instance, in the EPF10K50E device, the carry chain stops at the eighteenth LAB and a new one begins at the nineteenth LAB.

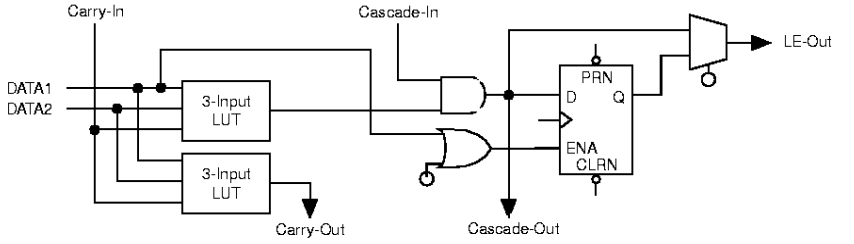
Figure 10 shows the LE operating modes.

Figure 10. FLEX 10KE LE Operating Modes

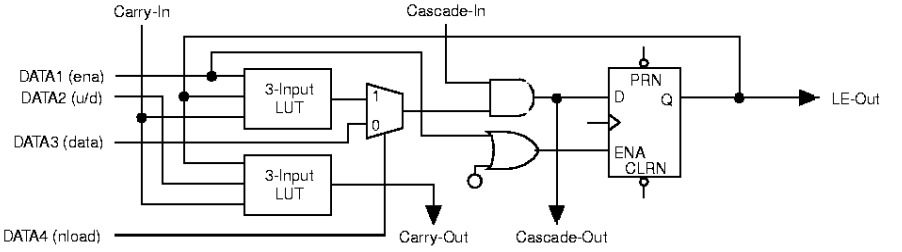
Normal Mode



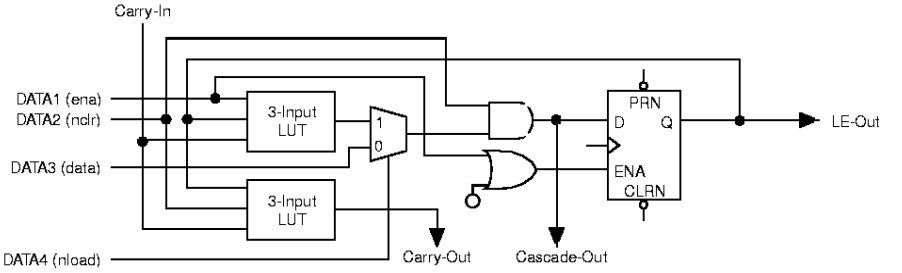
Arithmetic Mode



Up/Down Counter Mode



Clearable Counter Mode



FastTrack Interconnect Routing Structure

In the FLEX 10KE architecture, connections between LEs, EABs, and device I/O pins are provided by the FastTrack Interconnect routing structure, which is a series of continuous horizontal and vertical routing channels that traverse the device. This global routing structure provides predictable performance, even in complex designs. In contrast, the segmented routing in FPGAs requires switch matrices to connect a variable number of routing paths, increasing the delays between logic resources and reducing performance.

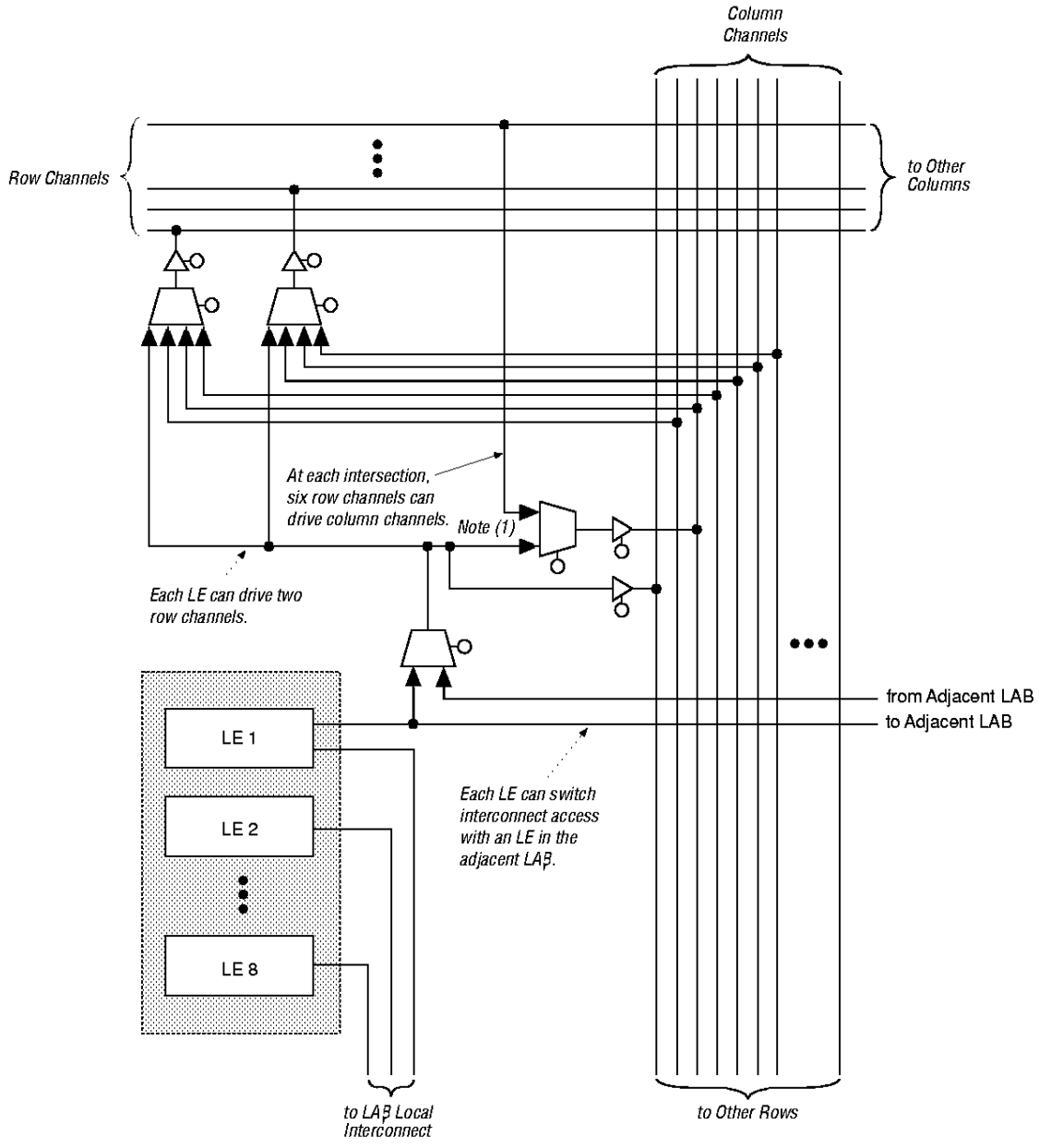
The FastTrack Interconnect routing structure consists of row and column interconnect channels that span the entire device. Each row of LABs is served by a dedicated row interconnect. The row interconnect can drive I/O pins and feed other LABs in the row. The column interconnect routes signals between rows and can drive I/O pins.

Row channels drive into the LAB or EAB local interconnect. The row signal is buffered at every LAB or EAB to reduce the effect of fan-out on delay. A row channel can be driven by an LE or by one of three column channels. These four signals feed dual 4-to-1 multiplexers that connect to two specific row channels. These multiplexers, which are connected to each LE, allow column channels to drive row channels even when all eight LEs in a LAB drive the row interconnect.

Each column of LABs or EABs is served by a dedicated column interconnect. The column interconnect that serves the EABs has twice as many channels as other column interconnects. The column interconnect can then drive I/O pins or another row's interconnect to route the signals to other LABs or EABs in the device. A signal from the column interconnect, which can be either the output of a LE or an input from an I/O pin, must be routed to the row interconnect before it can enter a LAB or EAB. Each row channel that is driven by an IOE or EAB can drive one specific column channel.

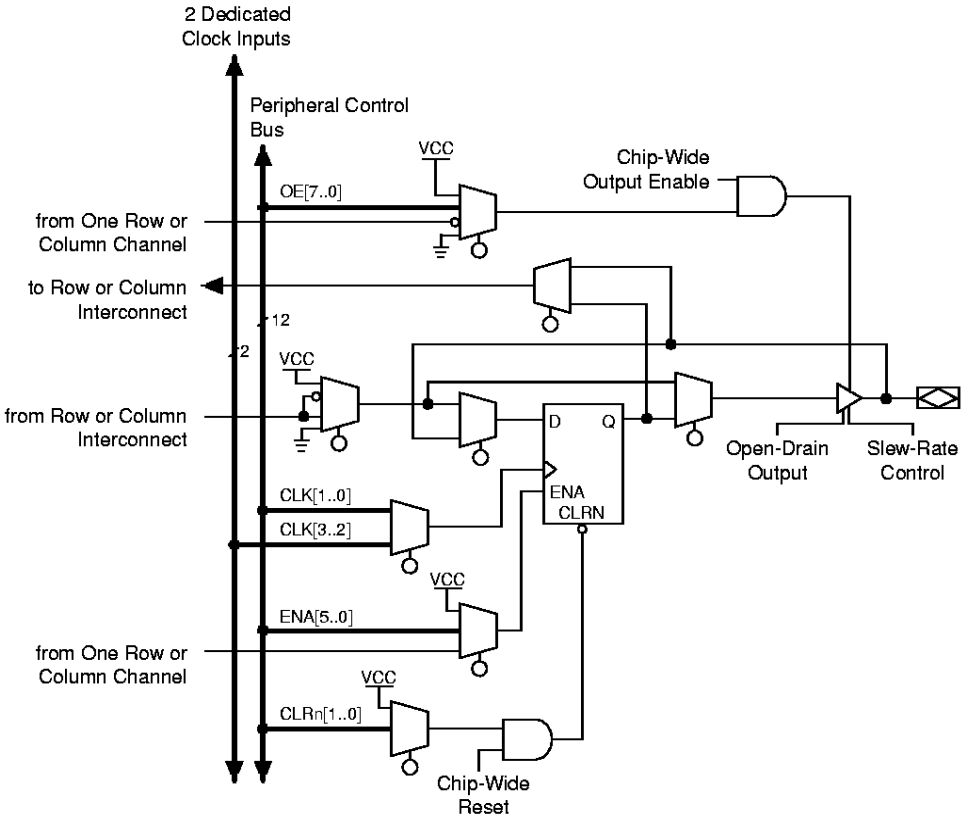
Access to row and column channels can be switched between LEs in adjacent pairs of LABs. For example, a LE in one LAB can drive the row and column channels normally driven by a particular LE in the adjacent LAB in the same row, and vice versa. This routing flexibility enables routing resources to be used more efficiently (see Figure 12).

Figure 12. FLEX 10KE LAβ Connections to Row & Column Interconnect



Note:
(1) In EPF10K100B devices, four row channels can drive column channels at each intersection.

Figure 14. FLEX 10KE I/O Element



Each IOE selects the clock, clear, clock enable, and output enable controls from a network of I/O control signals called the peripheral control bus. The peripheral control bus uses high-speed drivers to minimize signal skew across devices; it provides up to 12 peripheral control signals that can be allocated as follows:

- Up to eight output enable signals
- Up to six clock enable signals
- Up to two clock signals
- Up to two clear signals

Tables 8 and 9 list the sources for each peripheral control signal, and show how the output enable, clock enable, clock, and clear signals share 12 peripheral control signals. The tables also show the rows that can drive global signals.

Table 8. EPF10K30E & EPF10K50E Peripheral Bus Sources

Peripheral Control Signal	EPF10K30E	EPF10K50E
OE0	Row A	Row A
OE1	Row B	Row B
OE2	Row C	Row D
OE3	Row D	Row F
OE4	Row E	Row H
OE5	Row F	Row J
CLKENA0/CLK0/GLOBAL0	Row A	Row A
CLKENA1/OE6/GLOBAL1	Row B	Row C
CLKENA2/CLR0	Row C	Row E
CLKENA3/OE7/GLOBAL2	Row D	Row G
CLKENA4/CLR1	Row E	Row I
CLKENA5/CLK1/GLOBAL3	Row F	Row J

Table 9. EPF10K100β, EPF10K100E, EPF10K130E, EPF10K200E & EPF10K250E Peripheral βus Sources

Peripheral Control Signal	EPF10K100β EPF10K100E	EPF10K130E	EPF10K200E	EPF10K250E
OE0	Row A	Row C	Row G	Row E
OE1	Row C	Row E	Row I	Row G
OE2	Row E	Row G	Row K	Row I
OE3	Row L	Row N	Row R	Row P
OE4	Row I	Row K	Row O	Row M
OE5	Row K	Row M	Row Q	Row O
CLKENA0/CLK0/GLOBAL0	Row F	Row H	Row L	Row J
CLKENA1/OE6/GLOBAL1	Row D	Row F	Row J	Row H
CLKENA2/CLR0	Row B	Row D	Row H	Row F
CLKENA3/OE7/GLOBAL2	Row H	Row J	Row N	Row L
CLKENA4/CLR1	Row J	Row L	Row P	Row N
CLKENA5/CLK1/GLOBAL3	Row G	Row I	Row M	Row K

Signals on the peripheral control bus can also drive the four global signals, referred to as GLOBAL0 through GLOBAL3 in Tables 8 and 9. An internally generated signal can drive a global signal, providing the same low-skew, low-delay characteristics as a signal driven by an input pin. An LE drives the global signal by driving a row line that drives the peripheral bus, which then drives the global signal. This feature is ideal for internally generated clear or clock signals with high fan-out. However, internally driven global signals offer no advantage over the general-purpose interconnect for routing data signals.

The chip-wide output enable pin is an active-low pin that can be used to tri-state all pins on the device. This option can be set in the MAX+PLUS II software. The registers in the IOE can also be reset by the chip-wide reset pin.

Row-to-IOE Connections

When an IOE is used as an input signal, it can drive two separate row channels. The signal is accessible by all LEs within that row. When an IOE is used as an output, the signal is driven by a multiplexer that selects a signal from the row channels. Up to eight IOEs connect to each side of each row channel (see Figure 15).

Figure 15. FLEX 10KE Row-to-IOE Connections

The values for m and n are provided in Table 10.

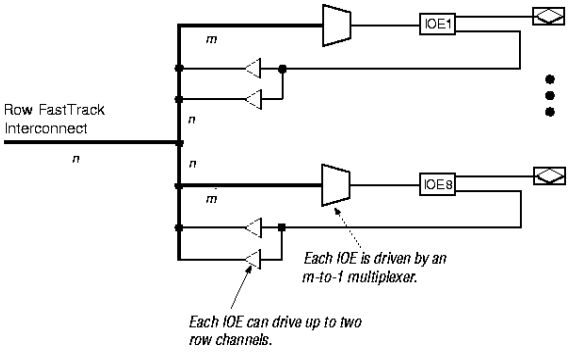
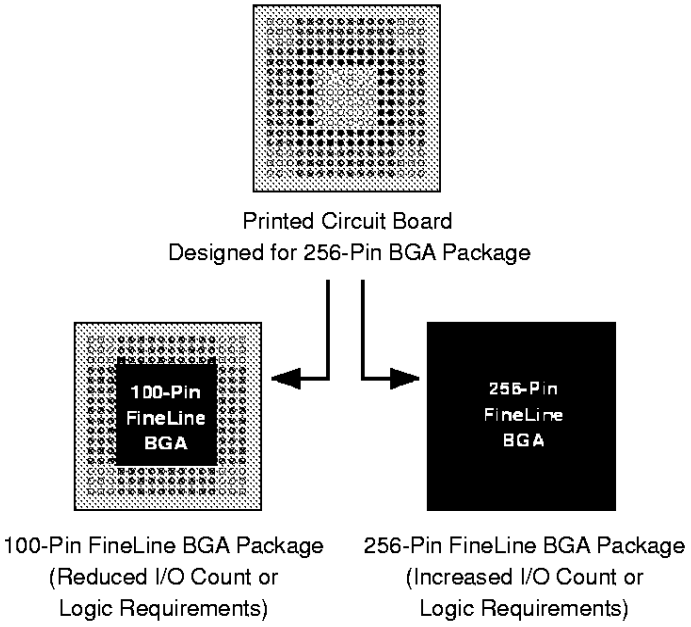


Table 10 lists the FLEX 10KE row-to-IOE interconnect resources.

Table 10. FLEX 10KE Row-to-IOE Interconnect Resources

Device	Channels per Row *(n)*	Row Channels per Pin *(m)*
EPF10K30E	216	27
EPF10K50E	216	27
EPF10K100B EPF10K100E	312	39
EPF10K130E	312	39
EPF10K200E	312	39
EPF10K250E	456	57

Figure 17. SameFrame Pin-Out Example



Output Configuration

This section discusses the peripheral component interconnect (PCI) pull-up clamping diode option, slew-rate control, open-drain output option, and MultiVolt I/O interface for FLEX 10KE devices. The PCI pull-up clamping diode, slew-rate control, and open-drain output options are controlled pin-by-pin via MAX+PLUS II logic options. The MultiVolt I/O interface is controlled by connecting VCCIO to a different voltage. Its effect can be simulated in the MAX+PLUS II software via a **Global Project Device Options** command (Assign menu).

PCI Pull-up Clamping Diode Option

FLEX 10KE devices have a pull-up clamping diode on every I/O, dedicated input, and dedicated clock pin. PCI clamping diodes clamp the signal to the V_{CCIO} value and are required for 3.3-V PCI compliance. Clamping diodes can also be used to limit overshoot in other systems.

Clamping diodes are controlled pin-by-pin. When V_{CCIO} is 3.3 V, a pin that has the clamping diode option turned on can be driven by a 2.5-V or 3.3-V signal, but not a 5.0-V signal. When V_{CCIO} is 2.5 V, a pin that has the clamping diode option turned on can be driven by a 2.5-V signal, but not a 3.3-V or 5.0-V signal. Additionally, a clamping diode can be activated for a subset of pins, which would allow a device to bridge between a 3.3-V PCI bus and a 5.0-V device.

Table 12 describes FLEX 10KE MultiVolt I/O support.

Table 12. FLEX 10KE MultiVolt I/O Support

V_{CCIO} (V)	Input Signal (V)			Output Signal (V)		
	2.5	3.3	5.0	2.5	3.3	5.0
2.5	✓	✓ (1)	✓ (1)	✓		
3.3	✓	✓	✓ (1)	✓ (2)	✓	✓

Notes:

(1) The PCI clamping diode must be disabled to drive an input with signals higher than V_{CCIO}.

(2) When V_{CCIO} = 3.3 V, a FLEX 10KE device can drive a 2.5-V device that has 3.3-V tolerant inputs.

Output pins on FLEX 10KE devices (with a pull-up resistor to the 5.0-V supply) can drive 5.0-V CMOS input pins that require a V_{IH} of 3.5 V. VCCIO should be connected to 3.3 V. When the I/O pin drives high, it will actively drive to VCCIO. The resistor will then pull the signal to 5.0 V. Because the FLEX 10KE device is 5.0-V tolerant, this operation will not affect the device. The PCI pull-up clamping diode must be disabled for any pin with a pull-up resistor to 5.0 V. The signal rise time is dependent on the value of the pull-up resistor and load impedance. When selecting a pull-up resistor, consider the I_{OL} current specification.

Figure 18 shows the timing requirements for the JTAG signals.

Figure 18. FLEX 10KE JTAG Waveforms

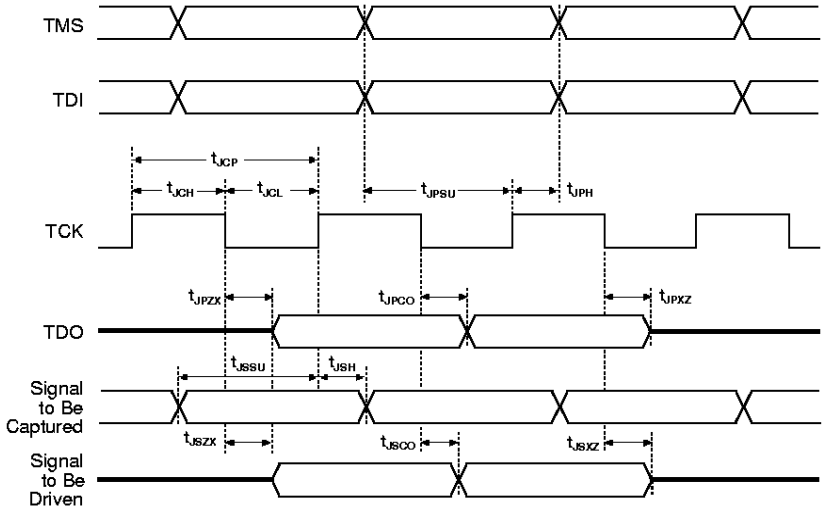


Table 14 shows the timing parameters and values for FLEX 10KE devices.

Table 14. FLEX 10KE JTAG Timing Parameters & Values

Symbol	Parameter	Min	Max	Unit
t_{JCP}	TCK clock period	100		ns
t_{JCH}	TCK clock high time	50		ns
t_{JCL}	TCK clock low time	50		ns
t_{JPSU}	JTAG port setup time	20		ns
t_{JPH}	JTAG port hold time	45		ns
t_{JPCO}	JTAG port clock to output		25	ns
t_{JPZX}	JTAG port high impedance to valid output		25	ns
t_{JPXZ}	JTAG port valid output to high impedance		25	ns
t_{JSSU}	Capture register setup time	20		ns
t_{JSH}	Capture register hold time	45		ns
t_{JSCO}	Update register clock to output		35	ns
t_{JSZX}	Update register high-impedance to valid output		35	ns
t_{JSXZ}	Update register valid output to high impedance		35	ns

Capacitance of FLEX 10KE Devices *Note (12)*

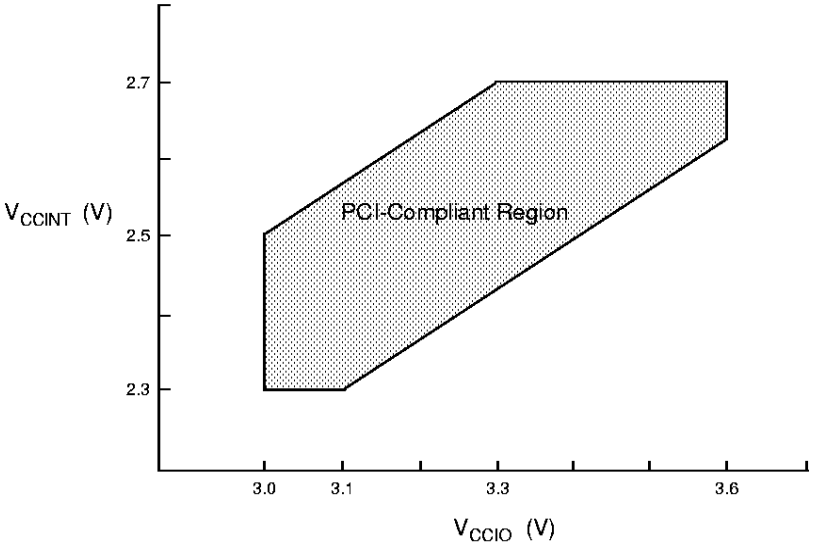
Symbol	Parameter	Conditions	Min	Max	Unit
C_{IN}	Input capacitance	V_{IN} = 0 V, f = 1.0 MHz		10	pF
C_{INCLK}	Input capacitance on dedicated clock pin	V_{IN} = 0 V, f = 1.0 MHz		12	pF

Notes to tables:

(1) See the *Operating Requirements for Altera Devices Data Sheet* in the ***1998 Data Book***.
(2) Minimum DC input is –0.3 V. During transitions, the inputs may undershoot to –2.0 V or overshoot to 5.7 V for periods shorter than 20 ns under no-load conditions.
(3) Numbers in parentheses are for industrial-temperature-range devices.
(4) Maximum V_{CC} rise time is 100 ms, and V_{CC} must rise monotonically.
(5) All pins, including dedicated inputs, clock, I/O, and JTAG pins, may be driven before V_{CCINT} and V_{CCIO} are powered.
(6) Typical values are for T_A = 25° C, V_{CCINT} = 2.5 V, and V_{CCIO} = 2.5 V or 3.3 V.
(7) These values are specified under "FLEX 10KE 2.5-V Device Recommended Operating Conditions" on page 42.
(8) The FLEX 10KE input buffers are compatible with 2.5-V, 3.3-V LVTTL and LVCMOS, 5.0-V TTL, and CMOS signals. Additionally, the input buffers are 3.3-V PCI compliant when V_{CCIO} and V_{CCINT} meet the relationship shown in Figure 20.
(9) The I_{OH} parameter refers to high-level TTL, PCI, or CMOS output current.
(10) The I_{OL} parameter refers to low-level TTL, PCI, or CMOS output current. This parameter applies to open-drain pins as well as output pins.
(11) Pin pull-up resistance values will be lower if the pin is driven higher than V_{CCIO} by an external source.
(12) Capacitance is sample-tested only.

Figure 20 shows the relationship between V_{CCIO} and V_{CCINT} for 3.3-V compliance.

Figure 20. Relationship between V_{CCIO} & V_{CCINT} for 3.3-V PCI Compliance



Configuration & Operation

The FLEX 10KE architecture supports several configuration schemes. This section summarizes the device operating modes and available device configuration schemes.

Operating Modes

The FLEX 10KE architecture uses SRAM configuration elements that require configuration data to be loaded every time the circuit powers up. The process of physically loading the SRAM data into the device is called *configuration*. Before configuration, as V_{CC} rises, the device initiates a Power-On Reset (POR). This POR event clears the device and prepares it for configuration. The FLEX 10KE POR time does not exceed 50 µs; however, when configuring with a Configuration EPROM, the Configuration EPROM imposes a 100 µs delay that allows system power to stabilize before configuration.

During initialization, which occurs immediately after configuration, the device resets registers, enables I/O pins, and begins to operate as a logic device. The I/O pins are tri-stated during power-up, and before and during configuration. Together, the configuration and initialization processes are called *command mode*; normal device operation is called *user mode*.

SRAM configuration elements allow FLEX 10KE devices to be reconfigured in-circuit by loading new configuration data into the device. Real-time reconfiguration is performed by forcing the device into command mode with a device pin, loading different configuration data, reinitializing the device, and resuming user-mode operation. The entire reconfiguration process requires less than 330 ms and can be used to reconfigure an entire system dynamically. In-field upgrades can be performed by distributing new configuration files.

Before and during configuration, all I/O pins (except dedicated inputs, clock, or configuration pins) are pulled high by a weak pull-up resistor.

Programming Files

Despite being function- and pin-compatible, FLEX 10KE devices are not programming- or configuration-file-compatible with FLEX 10K or FLEX 10KA devices. A design therefore must be recompiled before it is transferred from a FLEX 10K or FLEX 10KA device to an equivalent FLEX 10KE device. This recompilation should be performed both to create a new programming or configuration file and to check design timing in the faster FLEX 10KE device.

FLEX 10KE devices are generally pin-compatible with the equivalent FLEX 10KA device. In some cases, FLEX 10KE devices have fewer I/O pins than FLEX 10KA devices. Table 17 shows which FLEX 10KE devices have fewer I/Os. However, power, ground, JTAG, and configuration pins are the same on FLEX 10KA and FLEX 10KE devices, enabling migration from a FLEX 10KA design to a FLEX 10KE design.

Table 17. I/O Count on FLEX 10KA & FLEX 10KE Devices

FLEX 10KA		FLEX 10KE	
Device	**I/O Count**	**Device**	**I/O Count**
EPF10K30AF256	191	EPF10K30EF256	176
EPF10K30AF484	244	EPF10K30EF484	218
EPF10K30AB356	246	EPF10K30EB356	220
EPF10K50VF484	300	EPF10K50EF484	254
EPF10K50VB356	274	EPF10K50EB356	256
EPF10K100AF484	366	EPF10K100EF484	337
EPF10K130VB600	470	EPF10K130EB600	426

Configuration Schemes

The configuration data for a FLEX 10KE device can be loaded with one of five configuration schemes (see Table 18), chosen on the basis of the target application. An EPC2, EPC1, or EPC1441 Configuration EPROM, intelligent controller, or the JTAG port can be used to control the configuration of a FLEX 10KE device, allowing automatic configuration on system power-up.

Table 20. FLEX 10KE FineLine βGA Device Pin-Outs (Part 2 of 4) *Note (1)*

Pin Name	256-Pin FineLine βGA EPF10K30E	256-Pin FineLine βGA EPF10K50E EPF10K100E EPF10K100β	672-Pin FineLine βGA EPF10K130E	672-Pin FineLine βGA EPF10K200E EPF10K250E
DEV_CLRn *(3)*	D8	D8	J13	J13
DEV_OE *(3)*	C9	C9	H14	H14
VCCINT (2.5 V)	E11, F5, F7, F9, F12, H6, H7, H10, J7, J10, J11, K9, L5, L7, L9, L12, M11, R2	E11, F5, F7, F9, F12, H6, H7, H10, J7, J10, J11, K9, L5, L7, L9, L12, M11, R2	E13, E17, H2, H25, K16, L10, L12, L14, L17, M2, M25, N11, N12, N15, P12, P15, P16, R14, T2, T10,T12, T14, T17, T25, U16, Y7, AA23, AB10, AC14	E13, E17, H2, H25, K16, L10, L12, L14, L17, M2, M25, N11, N12, N15, P12, P15, P16, R14, T2, T10,T12, T14, T17, T25, U16, Y7, AA23, AB10, AC14
VCCIO (2.5 or 3.3 V)	D12, E6, F8, F10, G6, G8, G11, H11, J6, K6, K8, K11, L10, M6, N12	D12, E6, F8, F10, G6, G8, G11, H11, J6, K6, K8, K11, L10, M6, N12	C8, C15, D7, G3, J3, J17, K11, K22, L13, L15, M11, M13, M16, M22, N16, P11, R5, R11, R13, R16, R22, T15, U3, U11, V5, V17, V24, Y2, Y24, AA26, AD15	C8, C15, D7, G3, J3, J17, K11, K22, L13, L15, M11, M13, M16, M22, N16, P11, R5, R11, R13, R16, R22, T15, U3, U11, V5, V17, V24, Y2, Y24, AA26, AD15
GND	E5, E12, F6, F11, G7, G9, G10, H8, H9, J8, J9, K7, K10, L6, L11, M5, M12, T8	E5, E12, F6, F11, G7, G9, G10, H8, H9, J8, J9, K7, K10, L6, L11, M5, M12, T8	A2, A25, B2, B25, C3, C10, C24, D3, D4, D19, D23, D24, E4, E23, G23, J5, J23, K4, K10, K17, L11, L16, L22, M5, M12, M14, M15, N13, N14, P13, P14, P22, R12, R15, T11, T16, U10, U17, U24, V3, Y5, AA13, AA22, AB3, AB4, AB5, AB23, AB24, AC3, AC8, AC24, AD13, AD18, AE2, AE25, AF2, AF25	A2, A25, B2, B25, C3, C10, C24, D3, D4, D19, D23, D24, E4, E23, G23, J5, J23, K4, K10, K17, L11, L16, L22, M5, M12, M14, M15, N13, N14, P13, P14, P22, R12, R15, T11, T16, U10, U17, U24, V3, Y5, AA13, AA22, AB3, AB4, AB5, AB23, AB24, AC3, AC8, AC24, AD13, AD18, AE2, AE25, AF2, AF25

Table 20. FLEX 10KE FineLine βGA Device Pin-Outs (Part 3 of 4) *Note (1)*

Pin Name	256-Pin FineLine βGA EPF10K30E	256-Pin FineLine βGA EPF10K50E EPF10K100E EPF10K100β	672-Pin FineLine βGA EPF10K130E	672-Pin FineLine βGA EPF10K200E EPF10K250E
No Connect (N.C.)	D1, E3, E16, G3, H1, H16, J1, K3, K14, K16, L2, L4, M14, M16, N15	–	A4, A5, A6, A10, A11, A12, A13, A14, A15, A16, A17, A18, A19, A20, A21, A22, A23, A24, B4, B5, B6, B7, B8, B9, B10, B11, B12, B13, B16, B19, B20, B21, B22, B23, B24, C1, AE4, AE5, AE6, AE7, AE8, AE9, AE10, AE11, AE12, AE14, AE15, AE16, AE17, AF18, AE19, AE20, AE21, AE22, AE23, AF4, AF5, AF6, AF7, AF8, AF9, AF10, AF12, AF13, AF14, AF15, AF16, AF20, AF21, AF24, AF23	A3, A4, A5, A6, A8, A9, A10, A11, A12, A13, A14, A15, A16, A17, A18, A19, A20, A21, A22, A23, A24, B3, B4, B5, B6, B7, B8, B9, B10, B11, B12, B13, B14, B16, B19, B20, B21, B22, B23, B24, B26, C1, C25, C26, D1, D2, D25, D26, E1, E25, E26, F1, F25, G25, G26, H1, J1, J25, J26, K26, L2, L25, N2, P1, P2, R1, R26, T1, U1, U25, V1, V26, W1, Y26, AA1, AA2, AA25, AB2, AB25, AB26, AC1, AC2, AC25, AC26, AD2, AD26, AE1, AE3, AE4, AE5, AE6, AE7, AE8, AE9, AE10, AE11, AE12, AE14, AE15, AE16, AE17, AE19, AE20, AE21, AE22, AE23, AE24, AE26, AF3, AF4, AF5, AF6, AF7, AF8, AF9, AF10, AF11, AF12, AF13, AF14, AF15, AF16, AF17, AF18, AF20, AF21, AF23, AF24